ABSTRACT

ABRASIVE COMPOSITION AND USE OF THE SAME

An abrasive composition is provided comprising an oxidizing agent and abrasive particles which have a mean particle size of 2 $\mu$m or less, wherein each of the abrasive particles comprises (i) at least one oxide selected from aluminum oxide and silicon oxide and (ii) cerium oxide in an amount of 5% to 40% by weight in terms of cerium based on the oxide (i). A method for polishing and planarizing a metal layer formed on a semiconductor substrate using the abrasive composition is also provided .

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